Amendments to the Claims:

Claims 1, 3, 5, 7, 9, 10, 13-16, and 19 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1.

a memory module substrate;
a plurality of memory devices <u>disposed on the memory module substrate</u>; and
at least one non-volatile storage device <u>disposed on the memory module substrate</u>, the at least
<u>one non-volatile storage device configured for storing data indicating a location of</u>

(currently amended) A memory module, comprising:

- at least one failed part-refurbishable failure associated with at least one of the plurality of memory devices.
- 2. (Original) The memory module of claim 1, wherein the at least one non-volatile storage device is one of an EEPROM, an EPROM, a ferro-electronic device and a flash memory chip.
- 3. (currently amended) The memory module of claim 1, wherein the at least one failed part-refurbishable failure comprises at least one failed output.
- 4. (Original) The memory module of claim 1, wherein at least a portion of the plurality of memory devices are fully functional dice.
- 5. (currently amended) A computer system, comprising: a processor; and a memory module, comprising:

a memory module substrate;

- a plurality of memory devices <u>disposed on the memory module substrate</u>; and at least one non-volatile storage device <u>disposed on the memory module substrate</u>, the at <u>least one non-volatile storage device configured for storing data indicating a</u> location of at least one <u>failed part-refurbishable failure</u> associated with at least one of the plurality of memory devices.
- 6. (Original) The computer system of claim 5, wherein the at least one non-volatile storage device is at least one of an EEPROM, an EPROM, a ferro-electronic device and a flash memory chip.
- 7. (currently amended) The computer system of claim 65, wherein the at least one failed part-refurbishable failure comprises at least one failed output.
- 8. (Previously presented) The computer system of claim 5, wherein at least a portion of the plurality of memory devices are fully functional dice.
- 9. (currently amended) A method of testing a memory module, the method comprising:
- testing a memory module including <u>a memory module substrate and</u> a plurality of memory devices thereon disposed on the memory module substrate;
- identifying data indicative of a location of at least one failed part refurbishable failure associated with at least one of the plurality of memory devices; and storing the identified data on the memory module.
- 10. (currently amended) The method of claim 9, wherein storing the identified data of the at least one failed part refurbishable failure includes storing identification of at least one failed output.

- 11. (Previously presented) The method of claim 9, wherein storing the identification of the at least one failed output further comprises storing data in at least one non-volatile storage device on the memory module.
- 12. (Original) The method of claim 11, further comprising selecting the at least one non-volatile storage device from at least one of an EEPROM, an EPROM, a ferro-electronic device and a flash memory chip.
- 13. (currently amended) The method of claim 9, further comprising accessing the stored data and identifying a-the location of the at least one of the plurality of memory devices associated with the at least one failed part-refurbishable failure.
- 14. (currently amended) The method of claim 13, further comprising repairing or replacing memory devices on the memory module identified as having the at least one failed part refurbishable failure.
- 15. (currently amended) A method of fabricating a memory module, the method comprising:

placing a plurality of memory devices on a memory module substrate;

testing each of a plurality of elements associated with each of the plurality of memory devices on the memory module <u>substrate</u>; and

storing data indicative of a location of at least one memory device including at least one element which failed a test.

- 16. (currently amended) The method of claim 15, further comprising subsequently accessing the stored data indicative of the location of the at least one memory device including the at least one element which failed a the test.
 - 17. (Previously presented) The method of claim 16, further comprising identifying

the at least one memory device having the at least one failed element and repairing or replacing the at least one identified memory device on the memory module.

- 18. (Previously presented) The method of claim 17, further comprising testing the at least one repaired or replaced memory device on the memory module.
- 19. (currently amended) The method of claim 15, wherein storing the data indicative of the location of the at least one memory device including the at least one element which failed a the test includes storing data indicative of at least one failed output.